

F241/F4X

WIREBOND AOI MACHINE



Features:

- ❖ 3D Profiling Technology
- ❖ Inspect Wirebond, Die & Epoxy Defects
- ❖ Inspect Gold, Aluminum, Copper and Silver Wires
- ❖ Measures Ball, Wedge, Stitch and Loop Parameters
- ❖ Multi Stacked Die & Wires Inspection
- ❖ Modular & Scalable Design
- ❖ Cost-Effective
- ❖ High Throughput

SPECIFICATIONS

Item		Specification		
HANDLING	Magazine Size	Min 35(W) x 110(L) x 110(H) mm Max 130(W) x 310(L) x 160(H) mm		
	Substrate Size	Min 25(W) x 150(L) x 0.125(t) mm Max 120(W) x 300(L) x 1.5(t) mm		
	Load/Offload	Up to 3 Magazines		
	Handling	Conveyor/Gripper		
2D VISION	Magnification Options	1X	1.5X	2X
	Resolution ⁽¹⁾	3.45 um/pixel	2.3 um/pixel	1.72 um/pixel
	FOV ⁽¹⁾	14 X 10 mm	9.4 X 6.9 mm	7 X 5 mm
	DOV ⁽¹⁾	0.6 mm	0.4 mm	0.2 mm
	Inspection Time ⁽²⁾	80 SPH	40 SPH	20 SPH
	Illumination	Brightfield, Darkfield		
	LCD Display	2X 19 inch		
	Image Storage	All/Defect Image Saving		
	Operating System	MS Windows 10 [®]		
	Inspection Software	TTVISION [®] AOI TTVISION [®] OVS TTVISION [®] ORM		
REJECT HANDLING		E-Mapping		
COMMUNICATION		TCP/IP		
OPERATING ENVIRONMENT	Temperature	15 – 24	Degree C	
	Humidity	30 – 80	%	
	Cleanroom	Class 10000		
MTBA		> 60 Minutes		
MTBF		> 168 Hours		
PHYSICAL		1500(W) x 1200(D) x 1800(H) mm		
WEIGHT		900 KG		

Headquarter:

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